

IN THE CLAIMS

Please amend Claim 7 as shown in the attachment. A clean copy of the claims incorporating any amendment is shown below.

--7. (Amended) A wafer polishing head for planarizing a wafer, comprising:
a carrier for loading the wafer;
a retaining ring surrounding the carrier;
a first pressure chamber having a first inner pressure disposed above the retaining ring;
a second pressure chamber having a second inner pressure disposed on the carrier; and
an automatic control system respectively coupled to the first pressure chamber and the second pressure chamber for processing the first and second inner pressures as feedback digital signals, comparing the feedback digital signals, and producing digital signals from the feedback digital signals to control a relative height between the carrier and the retaining ring through the first and second pressure chambers.--

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1, 4-7 and 11 are now active in this application, Claim 7 having been amended by the present amendment.

In the outstanding official Office Action, Claims 1, 4-7 and 11 were rejected under 35 U.S.C. §102(e) as being anticipated by Nakashiba et al. (U.S. Patent 5,762,539).

Amended Claim 7 is fully supported by the specification, claims and drawings as originally filed. Applicants therefore submit that no new matter has been introduced.